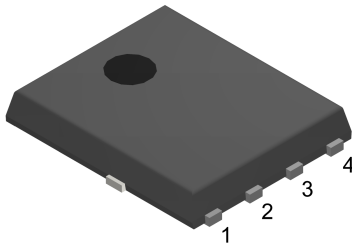
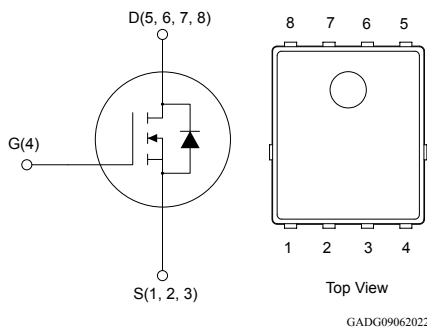


N-channel 80 V, 3.6 mΩ max., 156 A STripFET F8 Power MOSFET in a PowerFLAT 5x6 package


PowerFLAT 5x6


Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STL130N8F8	80 V	3.6 mΩ	156 A

- MSL1 grade
- 175 °C maximum operating junction temperature
- 100% avalanche tested
- Low gate charge Q_g

Applications

- Server and Telecom power
- Industrial battery management system (BMS)
- Power tools
- Drones

Description

The **STL130N8F8** is a 80 V N-channel enhancement mode Power MOSFET designed in STripFET F8 technology featuring an enhanced trench gate structure. It ensures a state-of-the-art of figure of merit for very low on-state resistance while reducing internal capacitances and gate charge for faster and more efficient switching.



Product status link

[STL130N8F8](#)

Product summary

Order code	STL130N8F8
Marking⁽¹⁾	130N8F8
Package	PowerFLAT 5x6
Packing	Tape and reel

1. For engineering samples marking, see the Section 3.3: PowerFLAT 5x6 marking information.

1 Electrical ratings

Table 1. Absolute maximum ratings (at $T_C = 25\text{ °C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	80	V
V_{GS}	Gate-source voltage	± 20	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25\text{ °C}^{(2)}$	156	A
	Drain current (continuous) at $T_C = 100\text{ °C}^{(2)}$	110	
	Drain current (continuous) at $T_C = 25\text{ °C}^{(3)}$	120	
$I_{DM}^{(1)(2)(4)}$	Drain current (pulsed), $t_p = 10\text{ }\mu\text{s}$	623	A
P_{TOT}	Total power dissipation at $T_C = 25\text{ °C}$	183	W
I_{AS}	Single pulse avalanche current (pulse width limited by maximum junction temperature)	60	A
E_{AS}	Single pulse avalanche energy (starting $T_J = 25\text{ °C}$, $I_D = 60\text{ A}$, $R_G = 25\text{ }\Omega$)	186	mJ
T_J	Operating junction temperature range	-55 to 175	$^{\circ}\text{C}$
T_{stg}	Storage temperature range		$^{\circ}\text{C}$

1. Specified by design, not tested in production.
2. This is the theoretical current value only related to the silicon.
3. This current value is limited by package.
4. Pulse width is limited by safe operating area.

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thJA}^{(1)}$	Thermal resistance, junction-to-ambient (on 2s2p FR-4 board vertical in still area)	15	$^{\circ}\text{C/W}$
R_{thJC}	Thermal resistance, junction-to-case	0.82	$^{\circ}\text{C/W}$

1. Defined according to JEDEC standards (JESD51-5, -7).

2 Electrical characteristics

$T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$	80			V
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 80\text{ V}$, $V_{GS} = 0\text{ V}$			1	μA
		$V_{DS} = 80\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 125\text{ }^{\circ}\text{C}^{(1)}$			100	
I_{GSS}	Gate-body leakage current	$V_{GS} = 20\text{ V}$, $V_{DS} = 0\text{ V}$			100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	2		4	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$, $I_D = 60\text{ A}$		2.9	3.6	m Ω
$R_G^{(1)}$	Gate resistance			0.8		Ω

1. Specified by design and evaluated by characterization, not tested in production.

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}^{(1)}$	Input capacitance	$V_{DS} = 40\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$	-	3510	-	pF
$C_{oss}^{(1)}$	Output capacitance		-	613	-	pF
$C_{rss}^{(1)}$	Reverse transfer capacitance		-	17	-	pF
$Q_g^{(1)}$	Total gate charge	$V_{DD} = 40\text{ V}$, $I_D = 60\text{ A}$, $V_{GS} = 0\text{ to }10\text{ V}$	-	55	-	nC
$Q_{gs}^{(1)}$	Gate-source charge		-	18	-	nC
$Q_{gd}^{(1)}$	Gate-drain charge		-	12	-	nC
$Q_{g(sync)}$	Total gate charge, sync. MOSFET	$V_{DS} = 0.1\text{ V}$, $V_{GS} = 0\text{ to }10\text{ V}$	-	35	-	nC
Q_{oss}	Output charge	$V_{DD} = 40\text{ V}$, $V_{GS} = 0\text{ V}$	-	63	-	nC

1. Specified by design and evaluated by characterization, not tested in production.

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}^{(1)}$	Turn-on delay time	$V_{DD} = 40\text{ V}$, $I_D = 60\text{ A}$, $R_G = 4.7\text{ }\Omega$, $V_{GS} = 10\text{ V}$	-	14	-	ns
$t_r^{(1)}$	Rise time		-	7	-	ns
$t_{d(off)}^{(1)}$	Turn-off delay time		-	31	-	ns
$t_f^{(1)}$	Fall time		-	9	-	ns

1. Specified by design and evaluated by characterization, not tested in production.

Table 6. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}^{(1)(2)}$	Forward on current (continuous)	$T_C = 25\text{ }^{\circ}\text{C}$	-		122	A
V_{SD}	Forward on voltage	$I_{SD} = 60\text{ A}$, $V_{GS} = 0\text{ V}$	-		1.2	V
$t_{rr}^{(1)}$	Reverse recovery time	$I_D = 30\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 64\text{ V}$	-	47		ns
$Q_{rr}^{(1)}$	Reverse recovery charge		-	50		nC
$I_{RRM}^{(1)}$	Reverse recovery current		-	2.1		A

1. Specified by design and evaluated by characterization, not tested in production.
2. This is the theoretical current value only related to the silicon.

2.1 Electrical characteristics (curves)

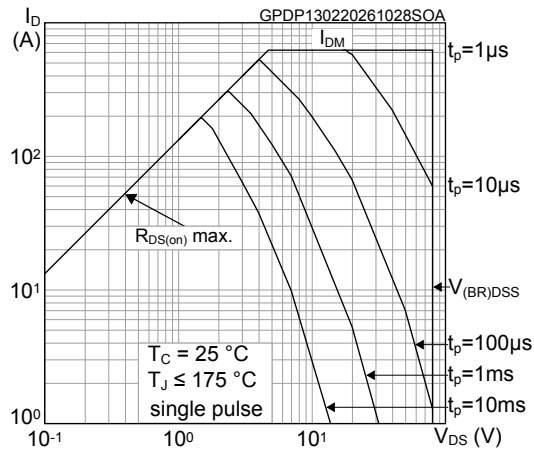
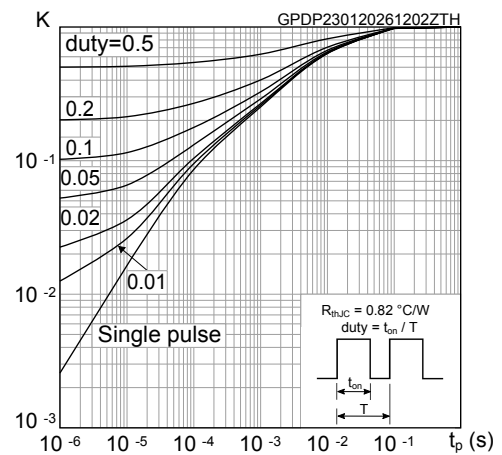
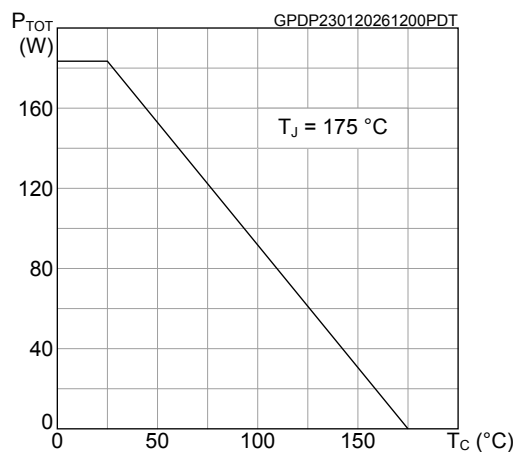
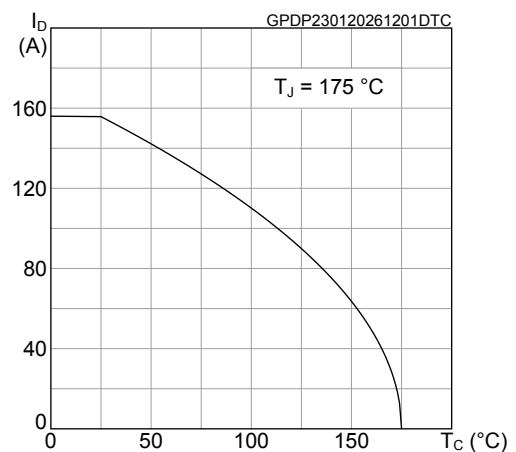
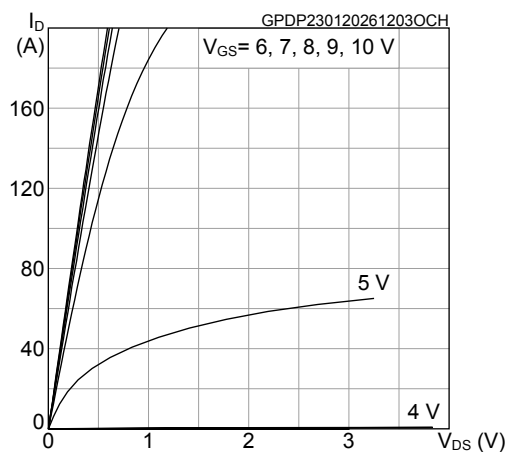
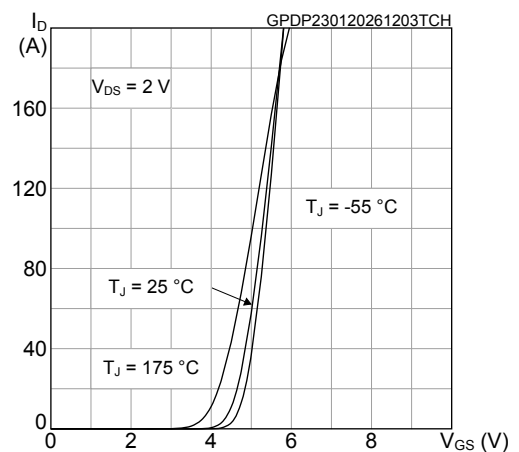
Figure 1. Safe operating area

Figure 2. Normalized transient thermal impedance

Figure 3. Total power dissipation

Figure 4. Drain current vs case temperature

Figure 5. Typical output characteristics

Figure 6. Typical transfer characteristics


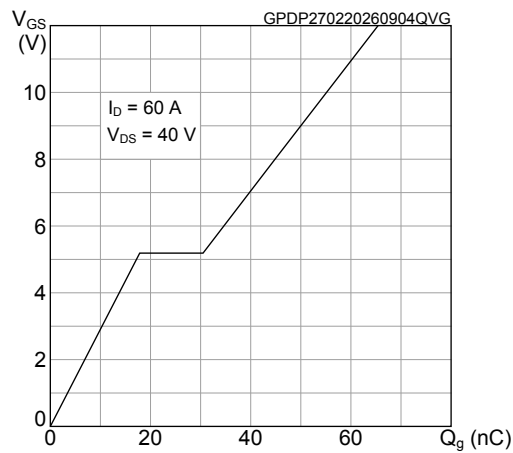
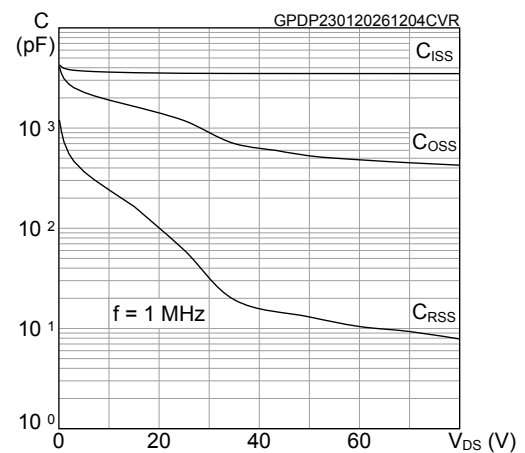
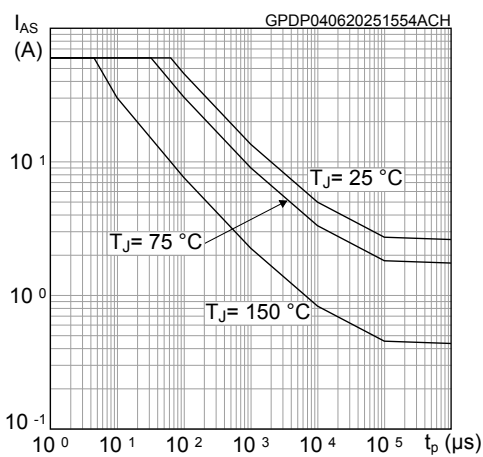
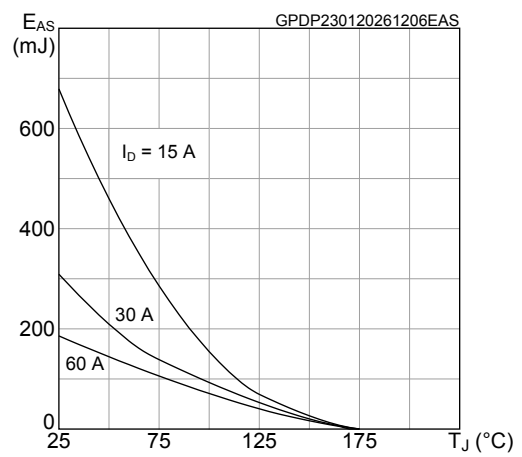
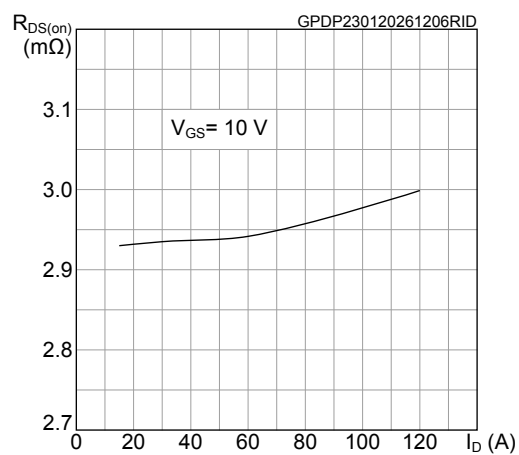
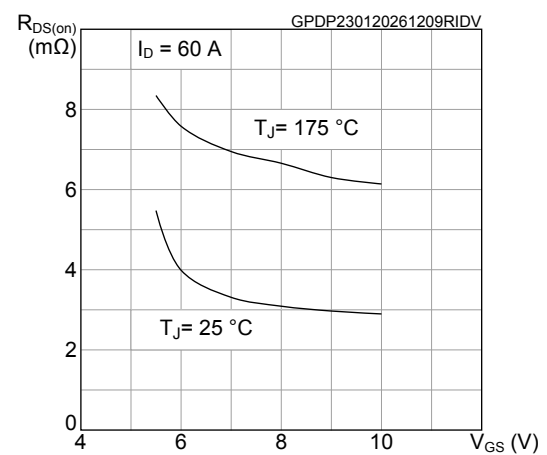
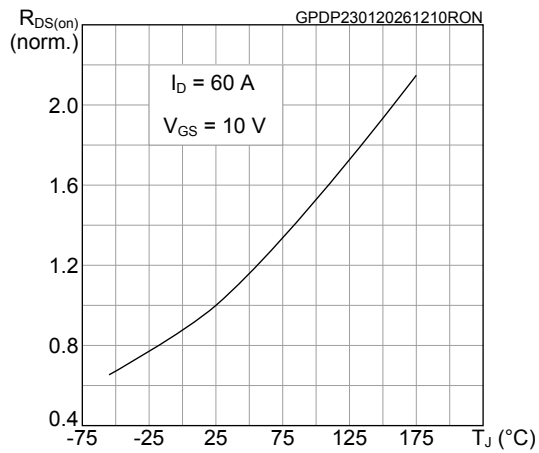
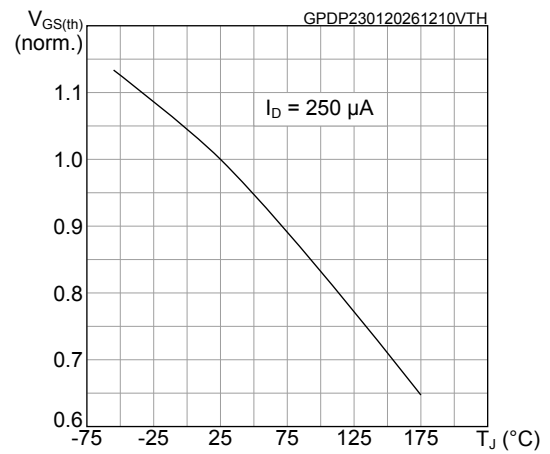
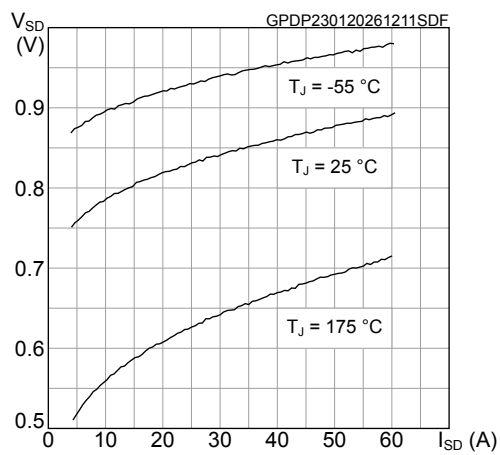
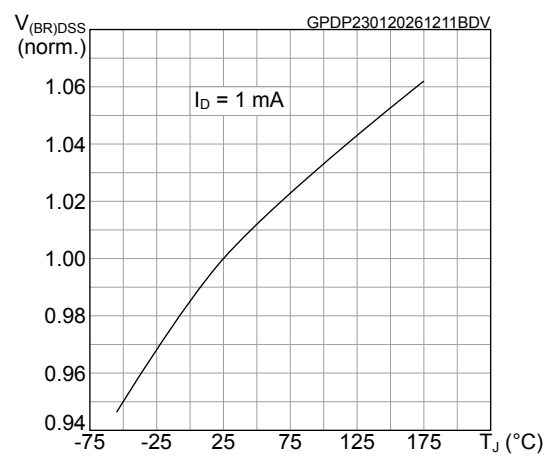
Figure 7. Typical gate charge characteristics

Figure 8. Typical capacitance characteristics

Figure 9. Avalanche characteristics

Figure 10. Avalanche energy

Figure 11. Typical drain-source on-resistance

Figure 12. Typical on-resistance vs. gate-source voltage


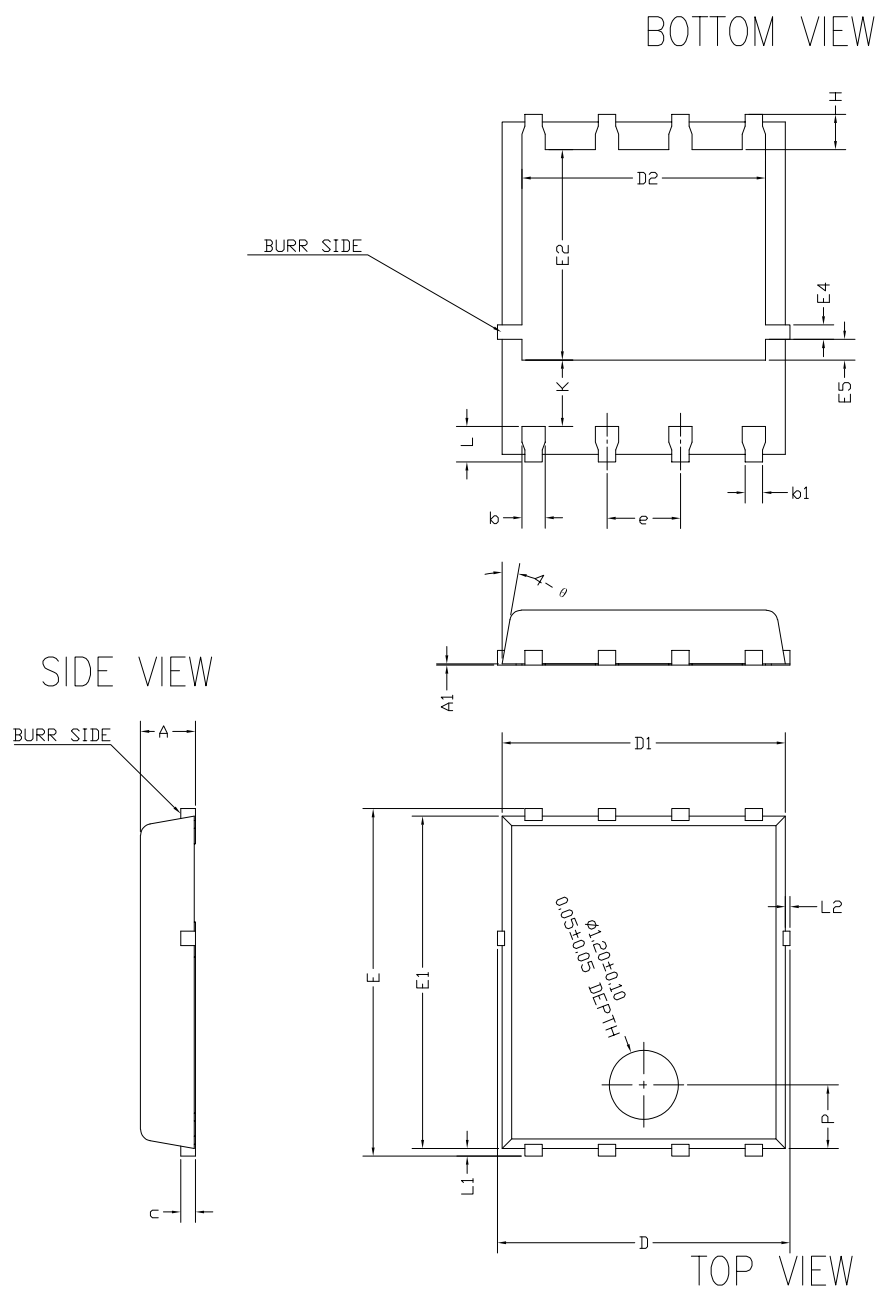
Figure 13. Normalized on-resistance vs temperature

Figure 14. Normalized gate threshold voltage vs temperature

Figure 15. Typical reverse diode forward characteristics

Figure 16. Normalized $V_{(BR)DSS}$ vs temperature


3 Package information

To meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

3.1 PowerFLAT 5x6 type B package information

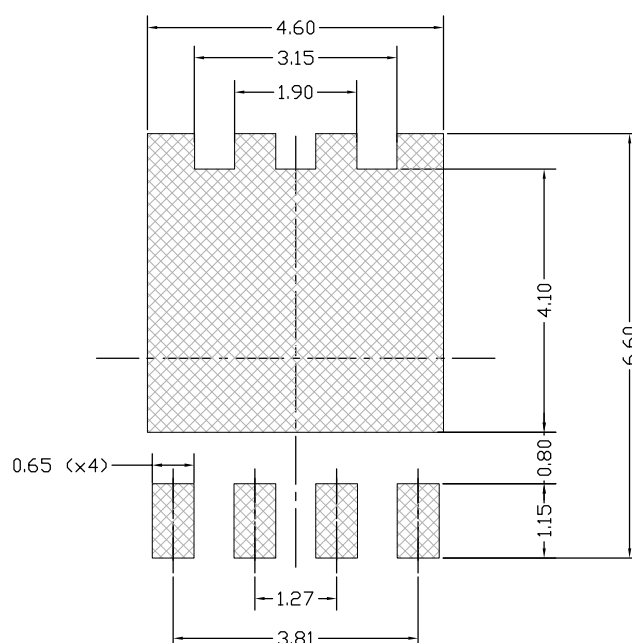
Figure 17. PowerFLAT 5x6 type B package outline



Drawing_8472137_typeB rev5

Table 7. PowerFLAT 5x6 type B mechanical data

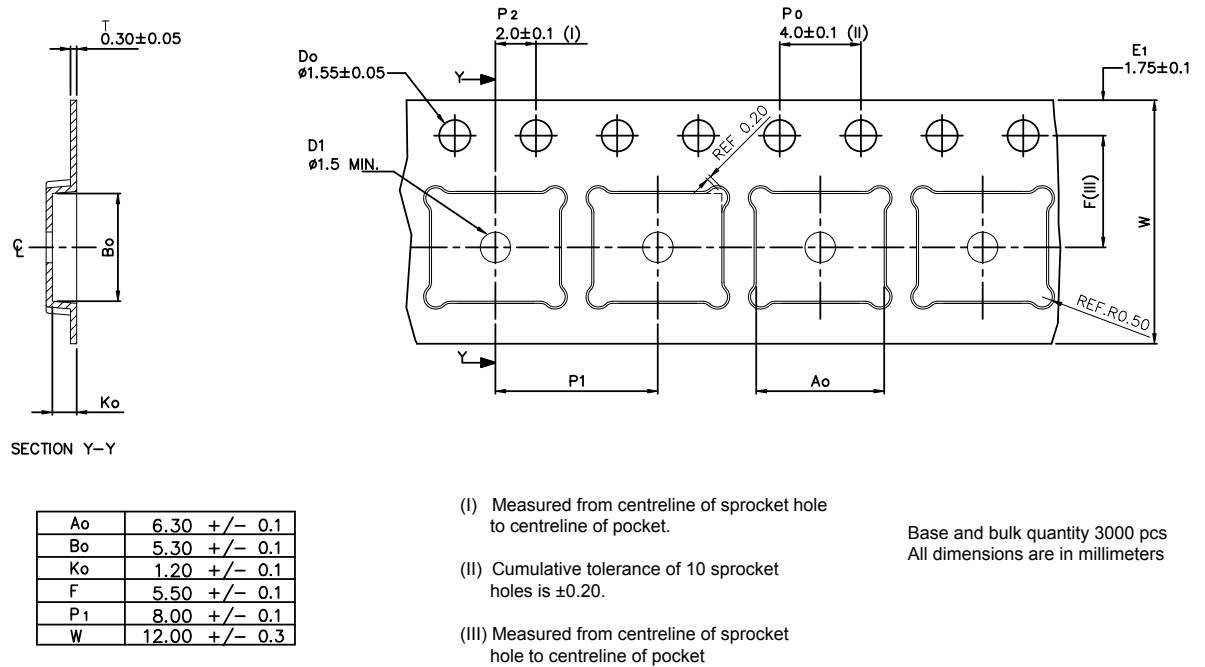
Dim.	mm		
	Min.	Typ.	Max.
A	0.90	0.95	1.00
A1		0.02	
b	0.35	0.40	0.45
b1		0.30	
c	0.21	0.25	0.34
D	4.80		5.10
D1	4.80	4.90	5.00
D2	4.01	4.21	4.31
e	1.17	1.27	1.37
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.54	3.64	3.74
E4	0.15	0.25	0.35
E5	0.26	0.36	0.46
H	0.51	0.61	0.71
K	0.95		
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
L2			0.10
P	1.00	1.10	1.20
θ	8°	10°	12°

Figure 18. PowerFLAT 5x6 recommended footprint (dimensions are in mm)


Footprint_8472137_typeB rev5

3.2 PowerFLAT 5x6 packing information

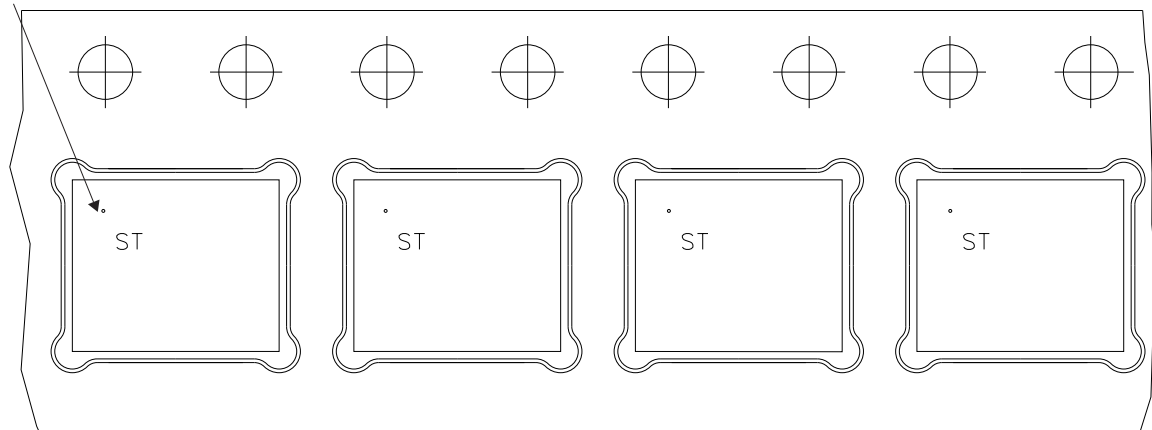
Figure 19. PowerFLAT 5x6 tape (dimensions are in mm)



8234350_Tape_rev_C

Figure 20. PowerFLAT 5x6 package orientation in carrier tape

Pin 1 identification



Technical drawing of a circular ESD mat, showing three views: a top view (left), a side view (middle), and a core detail (bottom left).

Top View (Left): Shows the circular mat with a central hole. Dimensions include:

- Outer diameter: $\varnothing 330 (+0/-4.0)$
- Inner diameter: $\varnothing 25.00$
- Radial distance from center to outer edge: $R25.00$
- Radial distance from center to inner hole: $\varnothing 4.00$
- Radial distance from center to the start of the mat body: $\varnothing 2.50$
- Angle of the mat body: 120°
- Angle of the mat body: $\varnothing A$
- Label: PART NO.

Side View (Middle): Shows the mat's profile. Dimensions include:

- Top radius: $R0.60$
- Top thickness: 1.90
- Bottom thickness: 2.50
- Top width: $W3$ $11.9/15.4$
- Bottom width: $W2$ 18.4 (max)
- Bottom width: $W1$ $12.4 (+2/-0)$
- Bottom diameter: $\varnothing N$ $178 (\pm 2.0)$
- Label: ESD LOGO

Core Detail (Bottom Left): Shows the internal structure of the mat. Dimensions include:

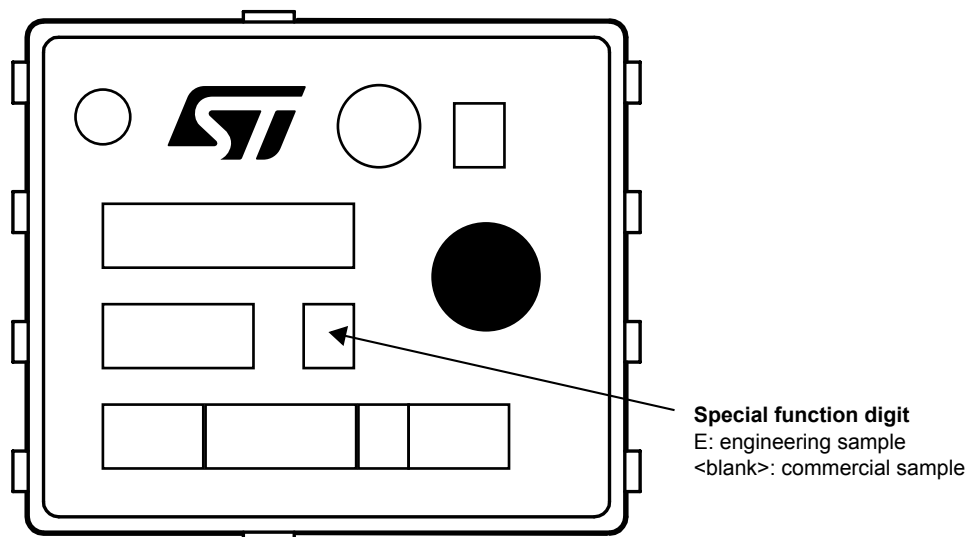
- Outer radius: $R1.10$
- Outer diameter: $\varnothing 21.2$
- Inner diameter: $\varnothing 13.00$
- Radial distance from center to outer edge: 2.20
- Label: CORE DETAIL

All dimensions are in millimeters.

8234350_Reel_rev_C

3.3 PowerFLAT 5x6 marking information

Figure 22. PowerFLAT 5x6 marking information



Note: *Engineering Samples: these samples can be clearly identified by a dedicated special symbol in the marking of each unit. These samples are intended to be used for electrical compatibility evaluation only; usage for any other purpose may be agreed only upon written authorization by ST. ST is not liable for any customer usage in production and/or in reliability qualification trials.*

Commercial Samples: fully qualified parts from ST standard production with no usage restrictions.

Revision history

Table 8. Document revision history

Date	Revision	Changes
19-Jun-2025	1	First release.
03-Mar-2026	2	Updated Section 1: Electrical ratings , Section 2: Electrical characteristics and Section 2.1: Electrical characteristics (curves) .

Contents

1	Electrical ratings	2
2	Electrical characteristics	3
2.1	Electrical characteristics (curves)	5
3	Package information	8
3.1	PowerFLAT 5x6 type B package information	8
3.2	PowerFLAT 5x6 packing information	10
3.3	PowerFLAT 5x6 marking information	12
	Revision history	13

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